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Datasheet of SN74ALVCH162835GR - IC UNIV BUS DVR 18BIT 56TSSOP

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## **Excellent Integrated System Limited**

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## FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Output Port Has Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

NOTE: For tape-and-reel order entry, the DGG package is abbreviated to GR, and the DGV package is abbreviated to VR.

## DESCRIPTION

This 18-bit universal bus driver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

Data flow from A to Y is controlled by the output-enable ( $\overline{OE}$ ) input. The device operates in the transparent mode when the latch-enable (LE) input is high. When LE is low, the A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

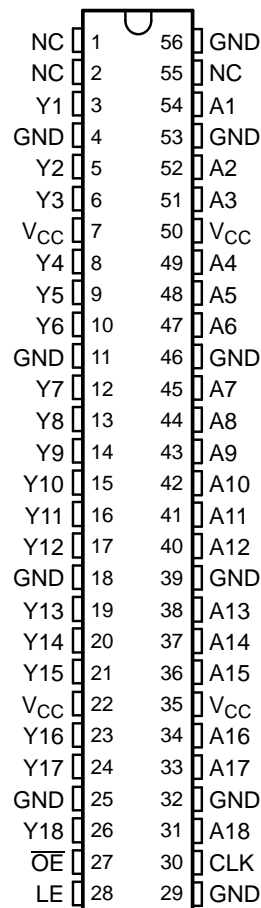
The output port includes equivalent 26-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162835 is characterized for operation from -40°C to 85°C.

## DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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**SN74ALVCH162835**

**18-BIT UNIVERSAL BUS DRIVER  
WITH 3-STATE OUTPUTS**

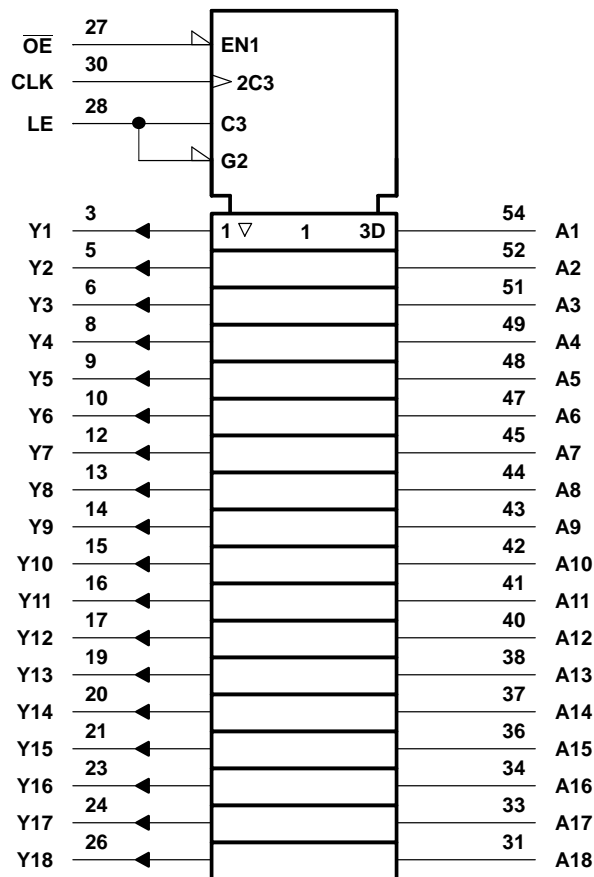
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**FUNCTION TABLE**

INPUTS				OUTPUT Y
$\overline{OE}$	LE	CLK	A	
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	L or H	X	$Y_0^{(1)}$

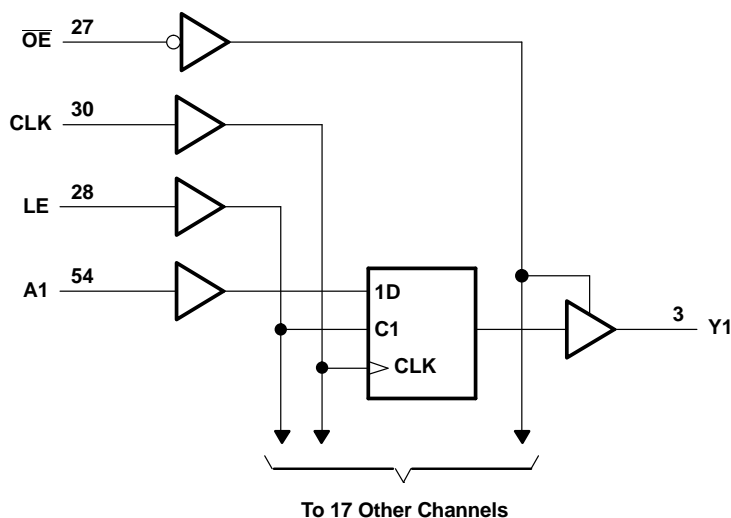
(1) Output level before the indicated steady-state input conditions were established

**LOGIC SYMBOL<sup>(1)</sup>**



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current		-50	mA
		$V_I < 0$		
$I_{OK}$	Output clamp current		-50	mA
		$V_O < 0$		
$I_O$	Continuous output current		$\pm 50$	mA
	Continuous current through each $V_{CC}$ or GND		$\pm 100$	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGG package	81	°C/W
		DGV package	86	
		DL package	74	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

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**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	1.65	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V	2	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8	
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V	-2	mA
		V <sub>CC</sub> = 2.3 V	-6	
		V <sub>CC</sub> = 2.7 V	-8	
		V <sub>CC</sub> = 3 V	-12	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	2	mA
		V <sub>CC</sub> = 2.3 V	6	
		V <sub>CC</sub> = 2.7 V	8	
		V <sub>CC</sub> = 3 V	12	
Δt/Δv	Input transition rise or fall rate		10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

(1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN TYP <sup>(1)</sup> MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2	V
	I <sub>OH</sub> = -2 mA	1.65 V	1.2	
	I <sub>OH</sub> = -4 mA	2.3 V	1.9	
	I <sub>OH</sub> = -6 mA	2.3 V	1.7	
		3 V	2.4	
	I <sub>OH</sub> = -8 mA	2.7 V	2	
	I <sub>OH</sub> = -12 mA	3 V	2	
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2	V
	I <sub>OL</sub> = 2 mA	1.65 V	0.45	
	I <sub>OL</sub> = 4 mA	2.3 V	0.4	
	I <sub>OL</sub> = 6 mA	2.3 V	0.55	
		3 V	0.55	
	I <sub>OL</sub> = 8 mA	2.7 V	0.6	
	I <sub>OL</sub> = 12 mA	3 V	0.8	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5	μA
I <sub>I(hold)</sub>	V <sub>I</sub> = 0.58 V	1.65 V	25	μA
	V <sub>I</sub> = 1.07 V	1.65 V	-25	
	V <sub>I</sub> = 0.7 V	2.3 V	45	
	V <sub>I</sub> = 1.7 V	2.3 V	-45	
	V <sub>I</sub> = 0.8 V	3 V	75	
	V <sub>I</sub> = 2 V	3 V	-75	
	V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V	±500	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	40	μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750	μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.5	pF
	Data inputs		6	
C <sub>o</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	7	pF

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

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WITH 3-STATE OUTPUTS**

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**TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
$f_{\text{clock}}$	Clock frequency	(1)		150		150		150		MHz	
$t_w$	Pulse duration	LE high		(1)		3.3		3.3		ns	
		CLK high or low		(1)		3.3		3.3			
$t_{\text{su}}$	Setup time	Data before CLK $\uparrow$		(1)		2.2		2.1		ns	
		Data before LE $\downarrow$	CLK high		(1)		1.9		1.6		
			CLK low		(1)		1.3		1.1		
$t_h$	Hold time	Data after CLK $\uparrow$		(1)		0.6		0.6		ns	
		Data after LE $\downarrow$	CLK high or low		(1)		1.4		1.7		

(1) This information was not available at the time of publication.

**SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			(1)		150		150		150		MHz
$t_{\text{pd}}$	A	Y	(1)		1 5		5		1 4.2		ns
	LE		(1)		1.3 5.9		5.8		1.3 5.1		
	CLK		(1)		1.4 6.3		6.1		1.4 5.4		
$t_{\text{en}}$	$\overline{\text{OE}}$	Y	(1)		1.4 6.3		6.5		1.1 5.5		ns
$t_{\text{dis}}$	$\overline{\text{OE}}$	Y	(1)		1 4.7		4.9		1.3 4.5		ns

(1) This information was not available at the time of publication.

**SWITCHING CHARACTERISTICS**

 from 0°C to 65°C,  $C_L = 50\text{ pF}$ 

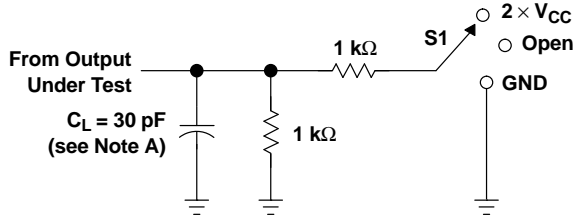
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\text{ V} \pm 0.15\text{ V}$		UNIT
			MIN	MAX	
$t_{\text{pd}}$	CLK	Y	1.9	5	ns

**OPERATING CHARACTERISTICS**
 $T_A = 25^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
$C_{\text{pd}}$	Outputs enabled	$C_L = 0, f = 10\text{ MHz}$	(1)	36	41	pF
	Outputs disabled		(1)	12.5	14	

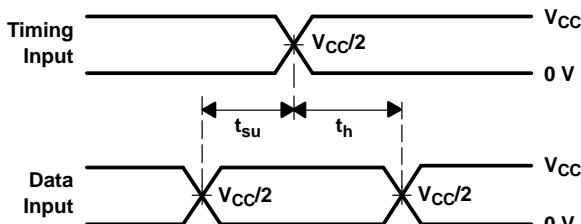
(1) This information was not available at the time of publication.

**PARAMETER MEASURE INFORMATION**  
 $V_{CC} = 1.8\text{ V}$

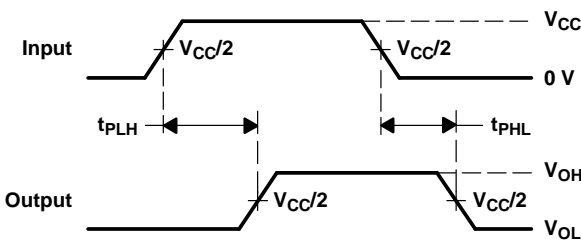


**LOAD CIRCUIT**

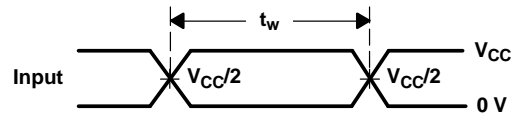
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



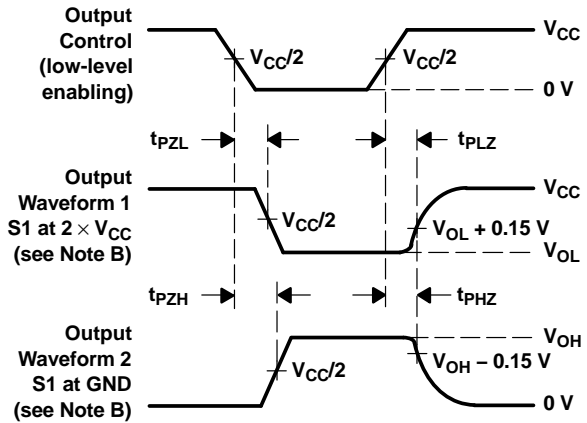
**VOLTAGE WAVEFORMS**  
**SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS**  
**PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS**  
**PULSE DURATION**



**VOLTAGE WAVEFORMS**  
**ENABLE AND DISABLE TIMES**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 1. Load Circuit and Voltage Waveforms**



**SN74ALVCH162835**

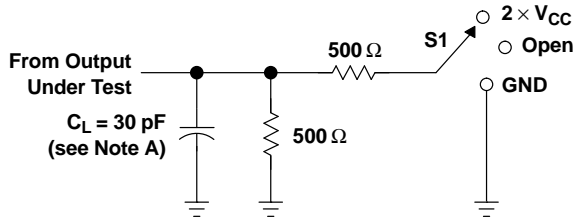
**18-BIT UNIVERSAL BUS DRIVER  
WITH 3-STATE OUTPUTS**

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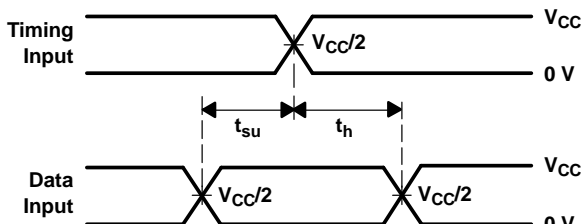
**PARAMETER MEASURE INFORMATION**

$V_{CC} = 2.5 V \pm 0.2 V$

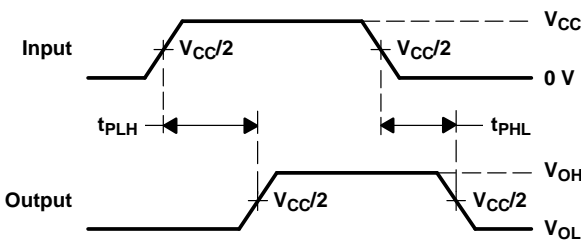


**LOAD CIRCUIT**

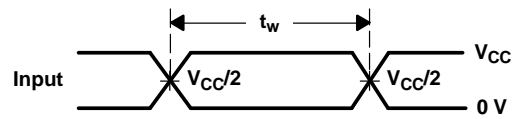
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



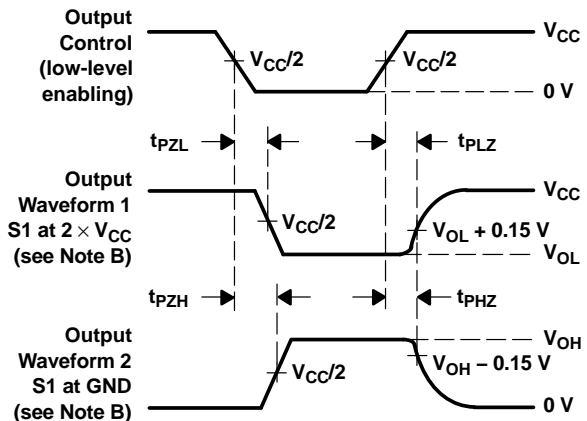
**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS  
PULSE DURATION**



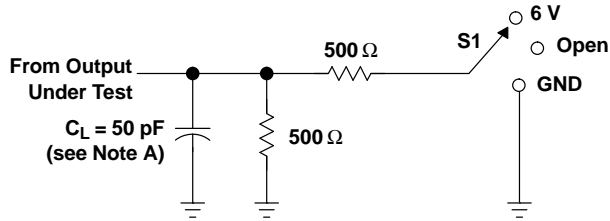
**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2 \text{ ns}$ ,  $t_f \leq 2 \text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 2. Load Circuit and Voltage Waveforms**

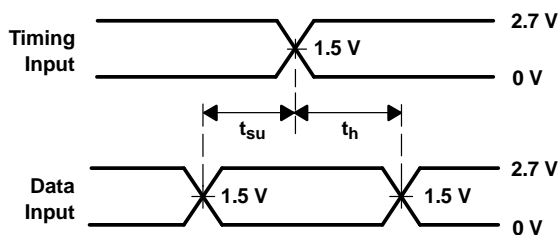
**PARAMETER MEASURE INFORMATION**

$V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

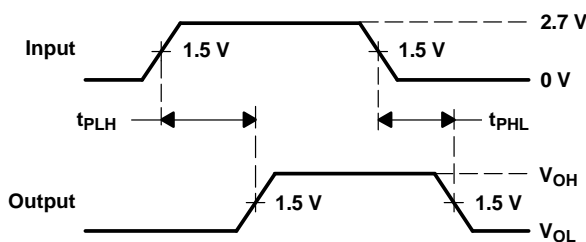


**LOAD CIRCUIT**

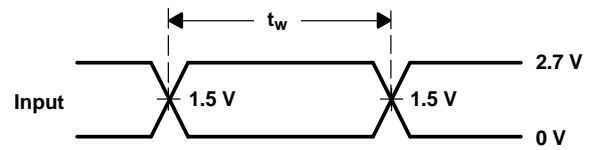
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



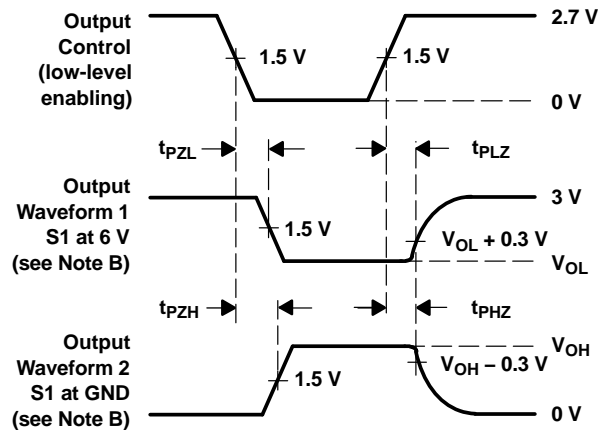
**VOLTAGE WAVEFORMS SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS PULSE DURATION**



**VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES**

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 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2.5\text{ ns}$ ,  $t_f \leq 2.5\text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 3. Load Circuit and Voltage Waveforms**



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH162835DGGR	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		
SN74ALVCH162835DGVR	OBSOLETE	TVSOP	DGV	56		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**PACKAGE OPTION ADDENDUM**

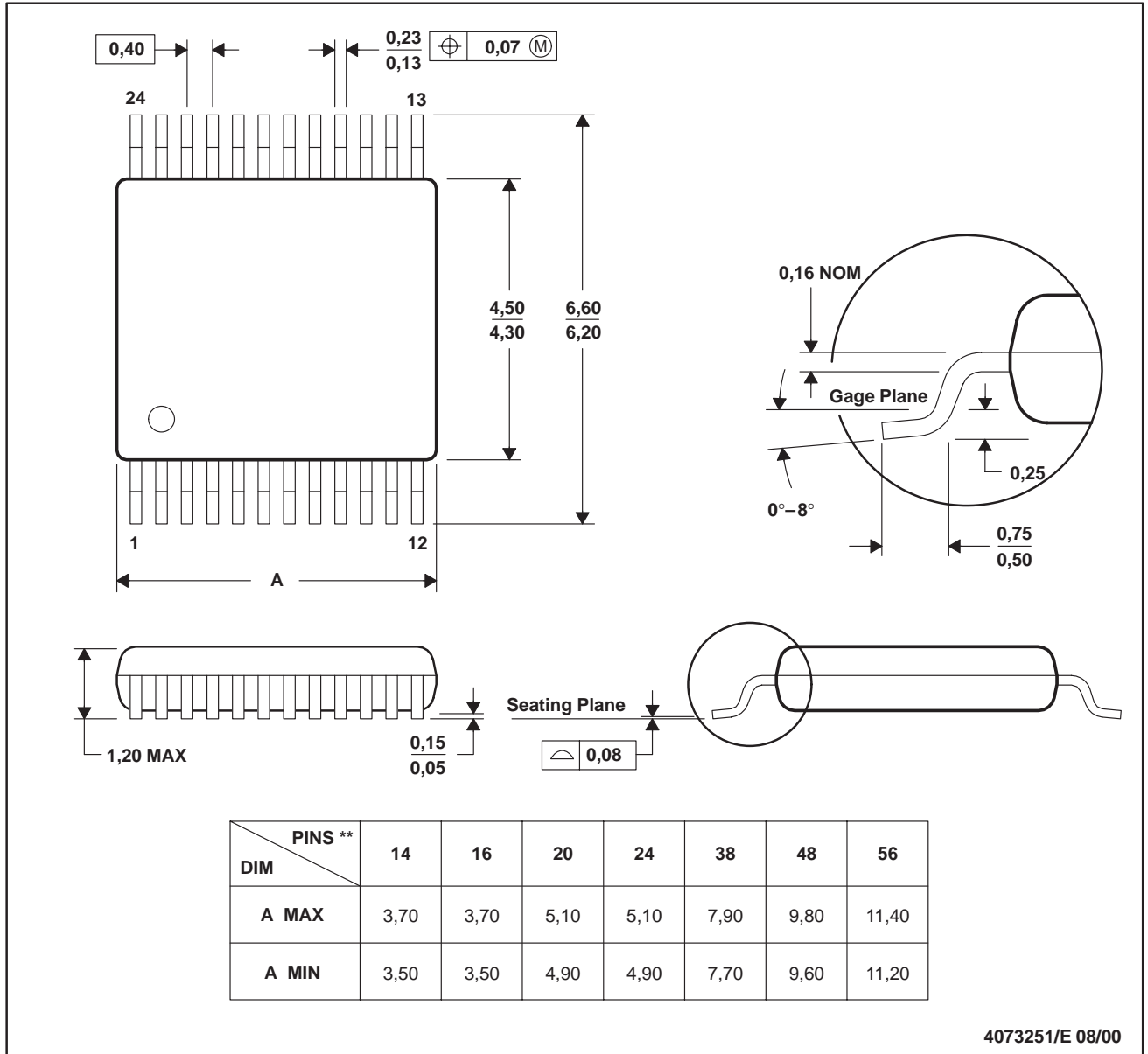
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MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

**DGV (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE**

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

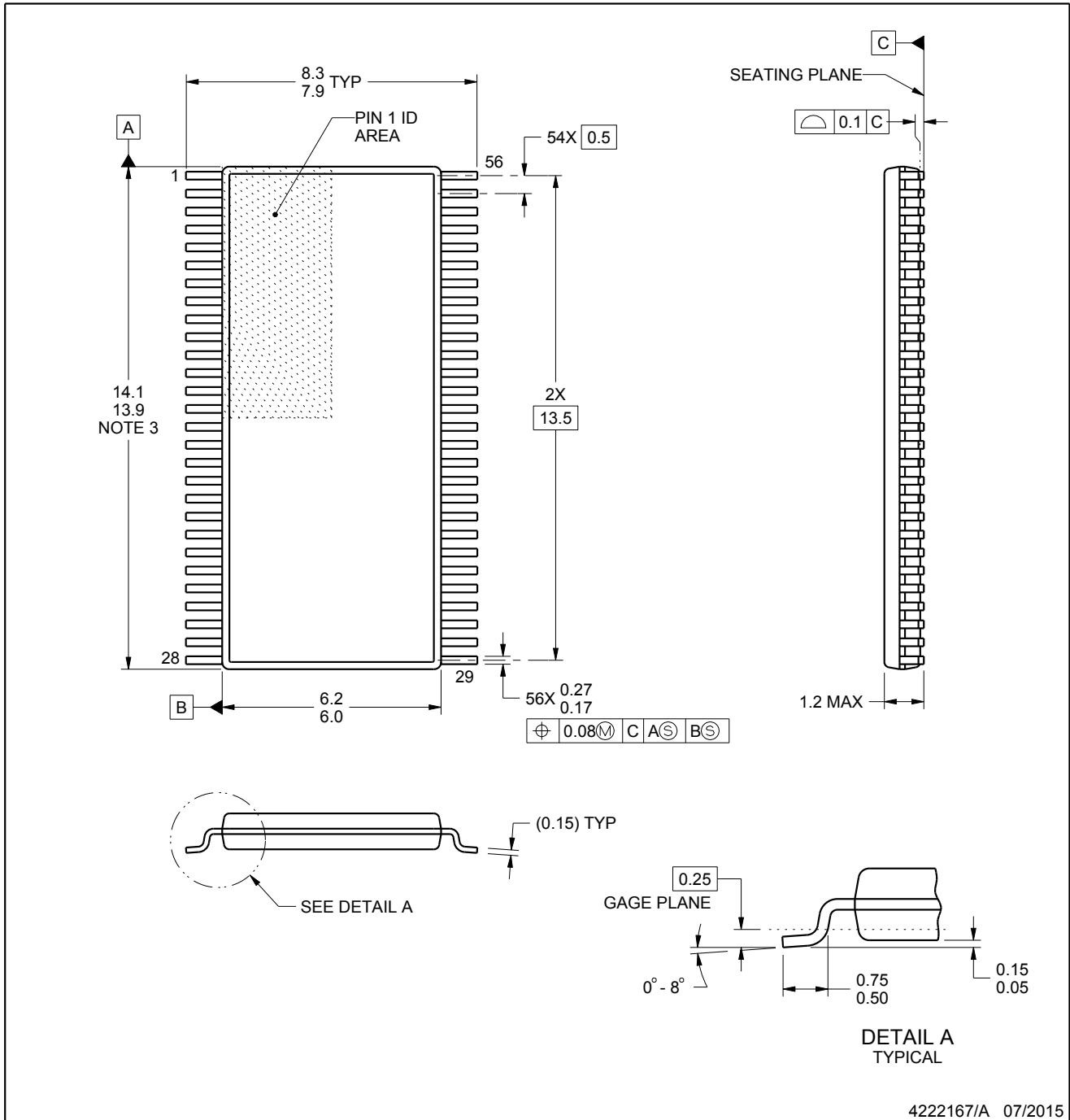


**PACKAGE OUTLINE**

**DGG0056A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4222167/A 07/2015

**NOTES:**

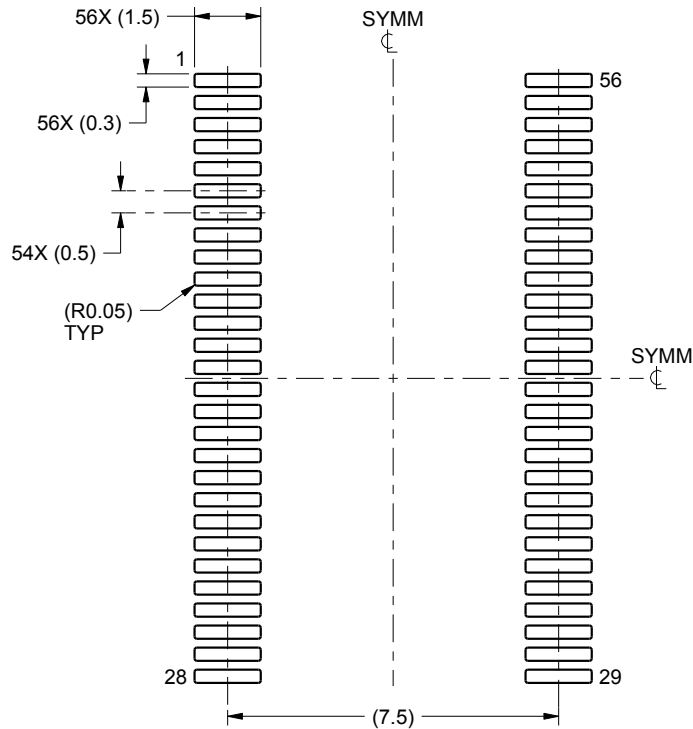
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

**EXAMPLE BOARD LAYOUT**

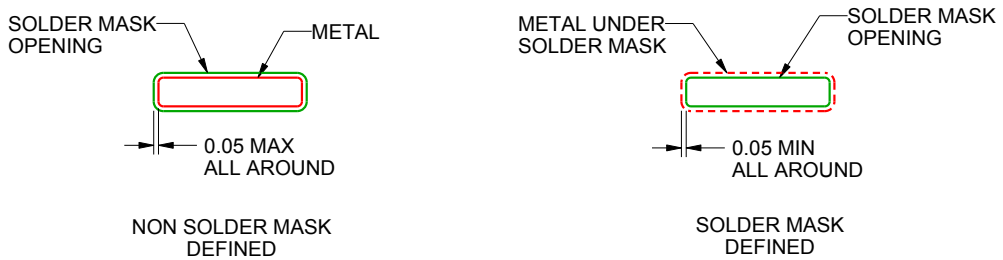
**DGG0056A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

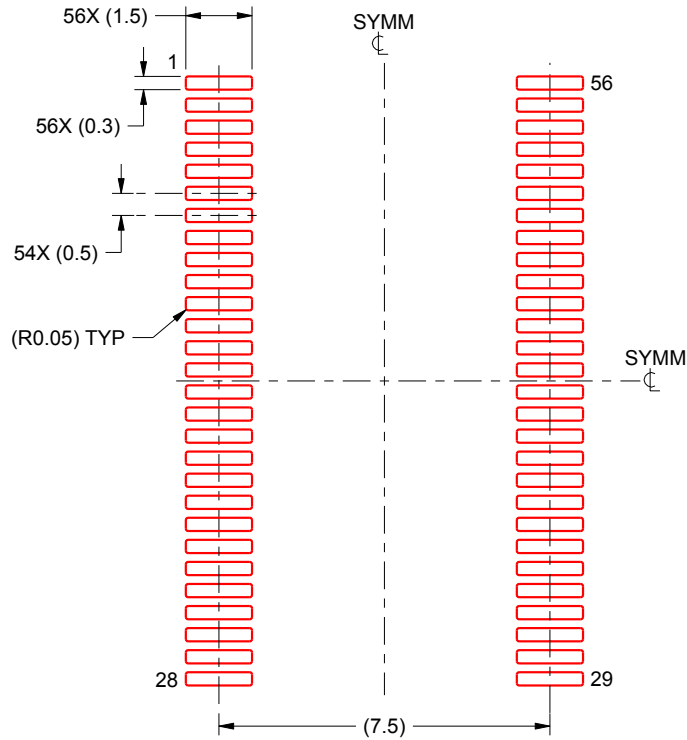
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

**EXAMPLE STENCIL DESIGN**

**DGG0056A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE:6X

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NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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